# **Analog Multiplexer/ Demultiplexer**

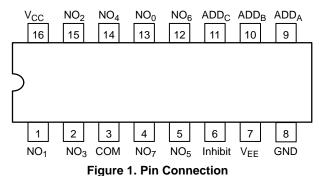
## TTL Compatible, Single-Pole, 8-Position **Plus Common Off**

The NLAST4051 is an improved version of the MC14051 and MC74HC4051 fabricated in sub-micron Silicon Gate CMOS technology for lower R<sub>DS(on)</sub> resistance and improved linearity with low current. This device may be operated either with a single supply or dual supply up to ±3 V to pass a 6 V<sub>PP</sub> signal without coupling capacitors.

When operating in single supply mode, it is only necessary to tie V<sub>EE</sub>, pin 7 to ground. For dual supply operation, V<sub>EE</sub> is tied to a negative voltage, not to exceed maximum ratings. Translation is provided in the device, the Address and Inhibit are standard TTL level compatible. For CMOS compatibility see NLAS4051. Pin for pin compatible with all industry standard versions of '4051.'

#### **Features**

- Improved R<sub>DS(on)</sub> Specifications
- Pin for Pin Replacement for MAX4051 and MAX4051A
  - One Half the Resistance Operating at 5.0 V
- Single or Dual Supply Operation
  - Single 3.0 5.0 V Operation, or Dual ±3 V Operation
  - With V<sub>CC</sub> of 3.0 to 3.3 V, Device Can Interface with 1.8 V Logic, No Translators Needed
  - Address and Inhibit Logic are Over-Voltage Tolerant and May Be Driven Up +6 V Regardless of V<sub>CC</sub>
- Address and Inhibit Pins Standard TTL Compatible
  - Greatly Improved Noise Margin Over MAX4051 and MAX4051A
  - True TTL Compatibility  $V_{IL} = 0.8 \text{ V}, V_{IH} = 2.0 \text{ V}$
- Improved Linearity Over Standard HC4051 Devices
- Space Saving TSSOP Package
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



(Top View)



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#### **MARKING DIAGRAM**



TSSOP-16 **DT SUFFIX** CASE 948F



= Assembly Location

= Wafer Lot Year = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

#### **TRUTH TABLE**

Inhibit		Address		ON SWITCHES*
	С	В	Α	
1	X don't care	X don't care	X don't care	All switches open
0	0	0	0	COM-NO <sub>0</sub>
0	0	0	1	COM-NO <sub>1</sub>
0	0	1	0	COM-NO <sub>2</sub>
0	0	1	1	COM-NO <sub>3</sub>
0	1	0	0	COM-NO <sub>4</sub>
0	1	0	1	COM-NO <sub>5</sub>
0	1	1	0	COM-NO <sub>6</sub>
0	1	1	1	COM-NO <sub>7</sub>

<sup>\*</sup>NO and COM pins are identical and interchangeable. Either may be considered an input or output; signals pass equally well in either direction.

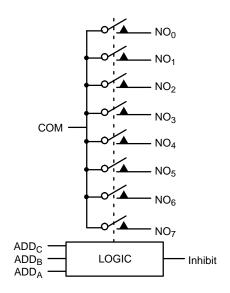


Figure 2. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol		Parameter	Value	Unit
V <sub>EE</sub>	Negative DC Supply Voltage	(Referenced to GND)	-7.0 to +0.5	V
V <sub>CC</sub>	Positive DC Supply Voltage (Note	1) (Referenced to GND) (Referenced to V <sub>EE</sub> )	-0.5 to +7.0 -0.5 to +7.0	V
V <sub>IS</sub>	Analog Input Voltage		$V_{EE}$ –0.5 to $V_{CC}$ +0.5	V
V <sub>IN</sub>	Digital Input Voltage	(Referenced to GND)	-0.5 to 7.0	V
I	DC Current, Into or Out of Any Pin		±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Cas	se for 10 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance		164	°C/W
P <sub>D</sub>	Power Dissipation in Still Air		450	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 > 1000	V
I <sub>LATCHUP</sub>	Latchup Performance	Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±300	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The absolute value of  $V_{CC} \pm |V_{EE}| \le 7.0$ . 2. Tested to EIA/JESD22–A114–A.

- 3. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V <sub>EE</sub>	Negative DC Supply Voltage	(Referenced to GND)	-5.5	GND	V
V <sub>CC</sub>	Positive DC Supply Voltage	(Referenced to GND) (Referenced to V <sub>EE</sub> )	2.5 2.5	5.5 6.6	V
V <sub>IS</sub>	Analog Input Voltage		V <sub>EE</sub>	V <sub>CC</sub>	V
V <sub>IN</sub>	Digital Input Voltage	(Note 6) (Referenced to GND)	0	5.5	V
T <sub>A</sub>	Operating Temperature Range, All Package Types		<b>-</b> 55	125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise/Fall Time (Channel Select or Enable Inputs)	$V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

			Vaa	Guara	nit		
Symbol	Parameter	Condition	V <sub>CC</sub> V	−55 to 25°C	≤85°C	≤125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage, Address or Inhibit Inputs		3.0 4.5 5.5	1.6 2.0 2.0	1.6 2.0 2.0	1.6 2.0 2.0	V
V <sub>IL</sub>	Maximum Low–Level Input Voltage, Address or Inhibit Inputs		3.0 4.5 5.5	0.5 0.8 0.8	0.5 0.8 0.8	0.5 0.8 0.8	V
I <sub>IN</sub>	Maximum Input Leakage Current, Address or Inhibit Inputs	V <sub>IN</sub> = 6.0 or GND	0 V to 6.0 V	±0.1	±1.0	±1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	Address or Inhibit and V <sub>IS</sub> = V <sub>CC</sub> or GND	6.0	4.0	40	80	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

### DC ELECTRICAL CHARACTERISTICS - Analog Section

			v <sub>cc</sub>	V <sub>EE</sub>	Guara	anteed Lin	nit	
Symbol	Parameter	Test Conditions	VCC	VEE	−55 to 25°C	≤85°C	≤125°C	Unit
R <sub>ON</sub>	Maximum "ON" Resistance	$V_{IN} = V_{IL} \text{ or } V_{IH}$ $V_{IS} = (V_{EE} \text{ to } V_{CC})$ $ I_S  = 10 \text{ mA}$ (Figures 4 thru 9)	3.0 4.5 3.0	0 0 -3.0	86 37 26	108 46 33	120 55 37	Ω
ΔR <sub>ON</sub>	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Pack- age	$\begin{aligned} V_{\text{IN}} &= V_{\text{IL}} \text{ or } V_{\text{IH}}, & V_{\text{IS}} &= 2.0 \text{ V} \\ V_{\text{IS}} &= 3.0 \text{ V} \\ V_{\text{IS}} &= 10 \text{ mA}, & V_{\text{IS}} &= 2.0 \text{ V} \end{aligned}$	3.0 4.5 3.0	0 0 -3.0	15 13 10	20 18 15	20 18 15	Ω
Rflat <sub>(ON)</sub>	ON Resistance Flatness	V <sub>COM</sub> = 1, 2, 3.5 V V <sub>COM</sub> = 2, 0, 2 V	4.5 3.0	3.0	4 2	4 2	5 3	Ω
I <sub>NC(OFF)</sub> I <sub>NO(OFF)</sub>	Maximum Off–Channel Leakage Current	Switch Off $V_{IN} = V_{IL}$ or $V_{IH}$ $V_{IO} = V_{CC} - 1.0 \text{ V or } V_{EE} + 1.0 \text{ V}$ (Figure 17)	6.0 3.0	0 -3.0	0.1 0.1	5.0 5.0	100 100	nA
I <sub>COM(ON)</sub>	Maximum On-Channel Leakage Current, Channel-to-Channel	Switch On $V_{IO} = V_{CC} - 1.0 \text{ V or } V_{EE} + 1.0 \text{ V}$ (Figure 17)	6.0 3.0	0 -3.0	0.1 0.1	5.0 5.0	100 100	nA

<sup>6.</sup> Unused digital inputs may not be left open. All digital inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

### AC CHARACTERISTICS (Input $t_r = t_f = 3 \text{ ns}$ )

						Guara	anteed Lin		
			Vcc	V <sub>EE</sub>	–55 to 25°C				
Symbol	Parameter	Test Conditions	٧	V	Min	Тур*	≤85°C	≤125°C	Unit
t <sub>BBM</sub>	Minimum Break-Before-Make Time	$\begin{array}{c} V_{IN} = V_{IL} \text{ or } V_{IH} \\ V_{IS} = V_{CC} \\ R_L = 300 \ \Omega, \ C_L = 35 \ \text{pF} \\ \text{(Figure 19)} \end{array}$	3.0 4.5 3.0	0.0 0.0 -3.0	1.0 1.0 1.0	6.5 5.0 3.5	- - -	- - -	ns

<sup>\*</sup>Typical Characteristics are at 25°C.

## AC CHARACTERISTICS ( $C_L = 35 \ pF$ , Input $t_r = t_f = 3 \ ns$ )

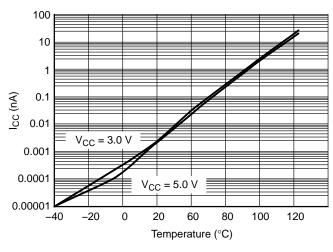
			Guaranteed Limit								
		V	V	_	-55 to 25	°C	≤8	35°C	≤1	25°C	
Symbol	Parameter	v <sub>cc</sub>	V <sub>EE</sub> V	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>TRANS</sub>	Transition Time (Address Selection Time) (Figure 18)	2.5 3.0 4.5 3.0	0 0 0 -3.0			40 28 23 23		45 30 25 25		50 35 30 28	ns
t <sub>ON</sub>	Turn-on Time (Figures 14, 15, 20, and 21) Enable to N <sub>O</sub> or N <sub>C</sub>	2.5 3.0 4.5 3.0	0 0 0 -3.0			40 28 23 23		45 30 25 25		50 35 30 28	ns
t <sub>OFF</sub>	Turn-off Time (Figures 14, 15, 20, and 21) Enable to N <sub>O</sub> or N <sub>C</sub>	2.5 3.0 4.5 3.0	0 0 0 -3.0			40 28 23 23		45 30 25 25		50 35 30 28	ns

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>IN</sub>	Maximum Input Capacitance, Select Inputs	8	pF
C <sub>NO</sub> or C <sub>NC</sub>	Analog I/O	10	
C <sub>COM</sub>	Common I/O	10	
C <sub>(ON)</sub>	Feedthrough	1.0	

## ADDITIONAL APPLICATION CHARACTERISTICS (GND = 0 V)

			V <sub>CC</sub>	V <sub>EE</sub>	Тур	
Symbol	Parameter	Condition	V	V	25°C	Unit
BW	Maximum On–Channel Bandwidth or Minimum Frequency Response	V <sub>IS</sub> = ½ (V <sub>CC</sub> - V <sub>EE</sub> ) Source Amplitude = 0 dBm (Figures 10 and 22)	3.0 4.5 6.0 3.0	0.0 0.0 0.0 -3.0	80 90 95 95	MHz
V <sub>ISO</sub>	Off-Channel Feedthrough Isolation	f = 100 kHz; $V_{IS} = \frac{1}{2} (V_{CC} - V_{EE})$ Source = 0 dBm (Figures 12 and 22)	3.0 4.5 6.0 3.0	0.0 0.0 0.0 -3.0	-93 -93 -93 -93	dB
V <sub>ONL</sub>	Maximum Feedthrough On Loss	V <sub>IS</sub> = ½ (V <sub>CC</sub> - V <sub>EE</sub> ) Source = 0 dBm (Figures 10 and 22)	3.0 4.5 6.0 3.0	0.0 0.0 0.0 -3.0	-2 -2 -2 -2	dB
Q	Charge Injection	$\begin{array}{l} V_{IN} = V_{CC} \text{ to } V_{EE, } f_{IS} = 1 \text{ kHz, } t_r = t_f = 3 \text{ ns} \\ R_{IS} = 0 \ \Omega, \ C_L = 1000 \text{ pF, } Q = C_L * \Delta V_{OUT} \\ \text{(Figures 16 and 23)} \end{array}$	5.0 3.0	0.0 -3.0	9.0 12	pC
THD	Total Harmonic Distortion THD + Noise	$\begin{split} f_{IS} &= 1 \text{ MHz, R}_L = 10 \text{ K}\Omega, C_L = 50 \text{ pF,} \\ V_{IS} &= 5.0 \text{ V}_{PP} \text{ sine wave} \\ V_{IS} &= 6.0 \text{ V}_{PP} \text{ sine wave} \\ \text{(Figure 13)} \end{split}$	6.0 3.0	0.0 -3.0	0.10 0.05	%

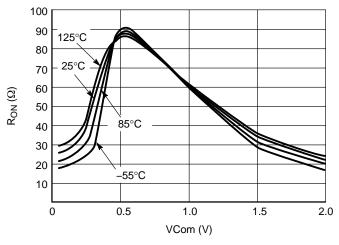
#### **TYPICAL CHARACTERISTICS**



100 80 2.0 V 60  $R_{ON}$  ( $\Omega$ ) 40 3.0 V 4.5 V 5.5 V  $\pm 3.3 \text{ V}$ 20 0 -4.0 -2.0 2.0 4.0 6.0 V<sub>IS</sub> (VDC)

Figure 3.  $I_{CC}$  versus Temp,  $V_{CC} = 3 \text{ V}$  and 5 V

Figure 4. R<sub>ON</sub> versus V<sub>CC</sub>, Temp = 25°C



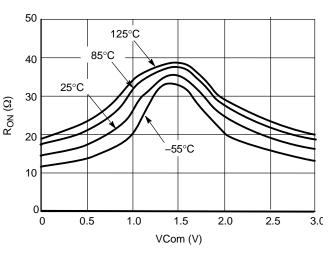
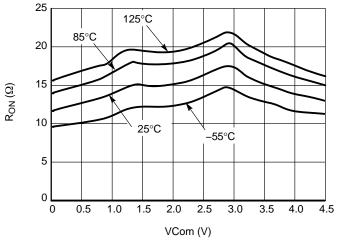


Figure 5. Typical On Resistance  $V_{CC}$  = 2.0 V,  $V_{EE}$  = 0 V

Figure 6. Typical On Resistance  $V_{CC}$  = 3.0 V,  $V_{EE}$  = 0 V



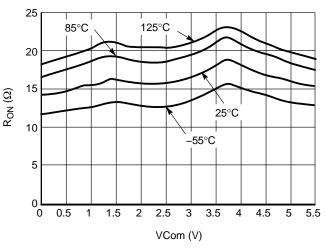


Figure 7. Typical On Resistance  $V_{CC}$  = 4.5 V,  $V_{EE}$  = 0 V

Figure 8. Typical On Resistance  $V_{CC} = 5.5 \text{ V}, V_{EE} = 0 \text{ V}$ 

#### TYPICAL CHARACTERISTICS

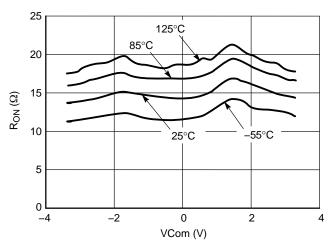


Figure 9. Typical On Resistance  $V_{CC}$  = 3.3 V,  $V_{EE}$  = -3.3 V

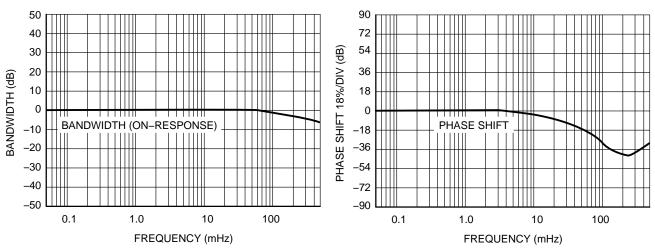


Figure 10. Bandwidth

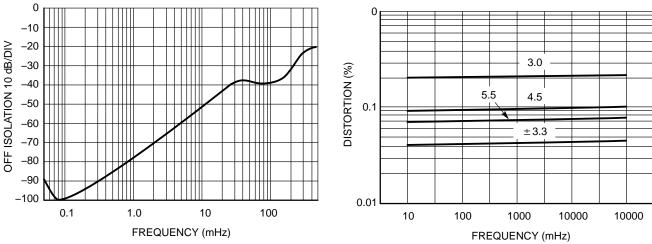
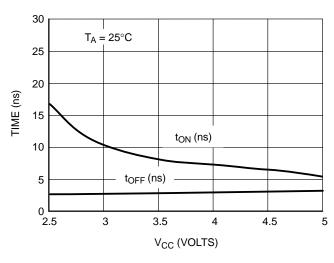


Figure 12. Off Isolation

Figure 13. Total Harmonic Distortion

Figure 11. Phase Shift

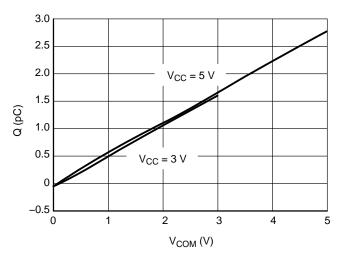
### **TYPICAL CHARACTERISTICS**



30  $V_{CC} = 4.5 \text{ V}$ 25 20 TIME (ns) 15 10  $t_{ON}$ 5  $t_{\mathsf{OFF}}$ 0 -55 -40 25 85 125 Temperature (°C)

Figure 14.  $t_{ON}$  and  $t_{OFF}$  versus  $V_{CC}$ 

Figure 15.  $t_{ON}$  and  $t_{OFF}$  versus Temp



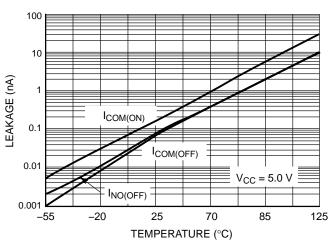


Figure 16. Charge Injection versus COM Voltage

Figure 17. Switch Leakage versus Temperature

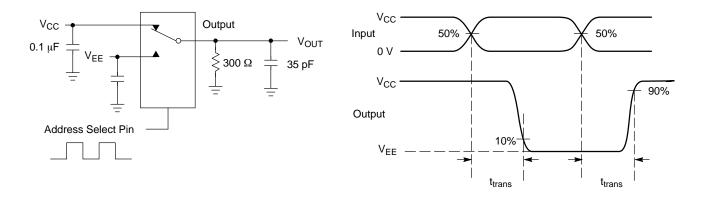


Figure 18. Channel Selection Propagation Delay

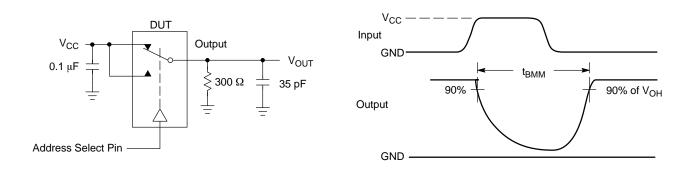


Figure 19. t<sub>BBM</sub> (Time Break-Before-Make)

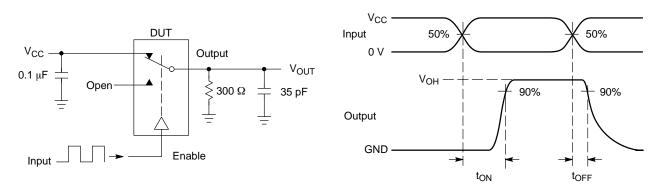


Figure 20. t<sub>ON</sub>/t<sub>OFF</sub>

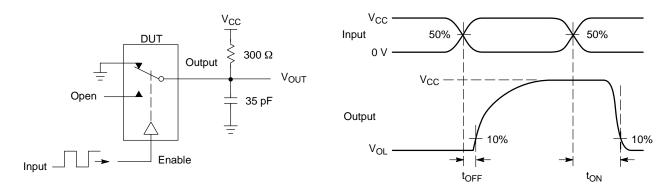
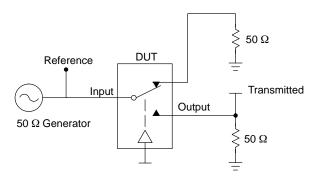


Figure 21. t<sub>ON</sub>/t<sub>OFF</sub>



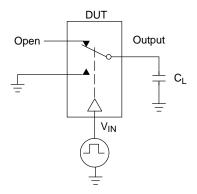
Channel switch Address and Inhibit/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch.  $V_{ISO}$ , Bandwidth and  $V_{ONL}$  are independent of the input signal direction.

$$V_{ISO}$$
 = Off Channel Isolation = 20 Log  $\left(\frac{V_{OUT}}{V_{IN}}\right)$  for  $V_{IN}$  at 100 kHz

$$V_{ONL}$$
 = On Channel Loss = 20 Log  $\left(\frac{V_{OUT}}{V_{IN}}\right)$  for  $V_{IN}$  at 100 kHz to 50 MHz

Bandwidth (BW) = the frequency 3 dB below V<sub>ONL</sub>

Figure 22. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V<sub>ONL</sub>



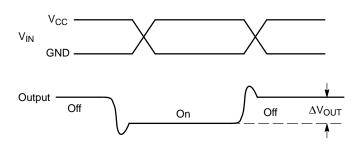
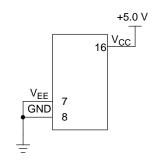
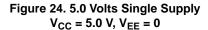


Figure 23. Charge Injection: (Q)

### **TYPICAL OPERATION**





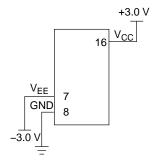


Figure 25. Dual Supply  $V_{CC} = 3.0 \text{ V}, V_{EE} = -3.0 \text{ V}$ 

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NLAST4051DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
NLVAST4051DTR2G*	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

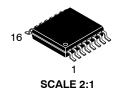
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

0.10 (0.004)

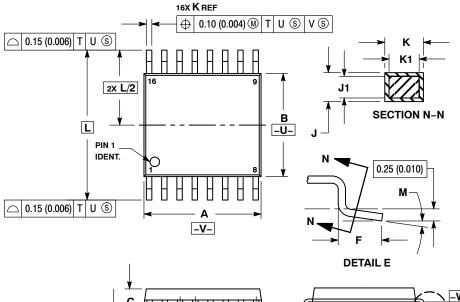
D

-T- SEATING PLANE



TSSOP-16 CASE 948F-01 ISSUE B

**DATE 19 OCT 2006** 



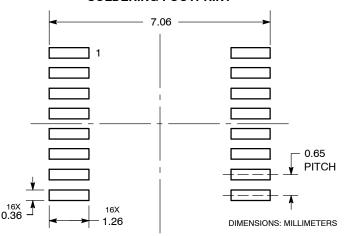
#### NOTES

- JIES:
  DIMENSIONING AND TOLERANCING PER
  ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A DOES NOT INCLUDE MOLD
  FLASH. PROTRUSIONS OR GATE BURRS.
  MOLD EL ROLL OF GATE BURDS SUAL NO.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.18	0.28	0.007	0.011
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252 BSC	
М	0 °	8 °	0 °	8 °

#### **SOLDERING FOOTPRINT**

G



#### **GENERIC MARKING DIAGRAM\***

168888888 XXXX XXXX **ALYW** 1<del>88888888</del>

XXXX = Specific Device Code Α = Assembly Location

= Wafer Lot L Υ = Year W = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98ASH70247A	Electronic versions are uncontrolled except when accessed directly from the Document Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	TSSOP-16		PAGE 1 OF 1			

**DETAIL E** 

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